

A Case for Comprehensive Design for Testability (DFT)

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This case study examines the challenges faced by an industrial customer during the production of a complex [Printed Circuit Board Assembly \(PCBA\)](#). The initial design lacked sufficient test points, leading to inadequate test coverage and a high failure rate during final product testing. To mitigate these issues, a strategic implementation of [Design for Testability \(DFT\)](#) was recommended and executed, resulting in significant improvements in product reliability and manufacturing efficiency.



Challenge:

The industrial customer manufactured a dense PCBA, integral to their critical product line. The original design, however, presented a significant hurdle: a lack of adequate test points. This limitation prevented comprehensive component-level testing and thorough functional verification during the manufacturing process. Consequently, a substantial number of defects remained undetected until the final product testing stage. This resulted in a high failure rate, leading to costly retesting, debugging, and rework, ultimately impacting production timelines and increasing overall manufacturing costs.

Strategy/Solution:

Recognizing the critical need for enhanced test coverage, INDIC proposed a fundamental shift in the PCBA design. The core of the solution involved the strategic addition of test points to the PCBA layout. This modification allowed for detailed component-level testing, enabling the identification and rectification of process and component defects early in the production cycle.

By implementing these design changes, INDIC facilitated a more granular testing approach. Component-level testing enabled the detection of subtle defects that would have otherwise slipped through the cracks, leading to failures in the final product. This proactive approach significantly improved the overall quality and reliability of the PCBAs.

Impact:

The implementation of DFT yielded substantial positive impacts on the customer's manufacturing process:

- **Reduced Final Testing Failures:** The enhanced test coverage at the component level directly translated to a significant reduction in failures during final product testing.
- **Reduced Dependency on Final Testing:** By capturing defects earlier in the process, the reliance on final testing as the primary defect detection mechanism was significantly reduced.
- **Increased First Pass Yield:** The proactive identification and rectification of defects resulted in a notable increase in the first-pass yield at final testing, minimizing the need for rework and retesting.
- **Reduced Cost of Retesting, Debug, and Rework:** The decrease in final testing failures and subsequent retesting significantly reduced the associated costs, leading to substantial savings for the customer.

Comprehensive Design for Testability (DFT) Conclusion:

This case study highlights the critical importance of incorporating DFT principles into the design of complex PCBAs. By strategically adding test points and enabling comprehensive component-level testing, the industrial customer achieved significant improvements in product reliability and manufacturing efficiency.

The implementation of DFT resulted in:

- Substantial improvements in failure rates and associated costs.

- Enhanced test coverage, ensuring a more robust product.
- A significant reduction in the probability of field failures, bolstering customer confidence and product longevity.

The success of this project underscores the value of proactive design considerations in minimizing manufacturing risks and maximizing product quality. The investment in DFT ultimately translated into a more efficient, reliable, and cost-effective production process.

Learn more about Comprehensive Design for Testability (DFT):

[Printed Circuit Board Assembly \(PCBA\), Design for Testability \(DFT\)](#)